

/ Descriptions

SOD-123

Silicon Diode in a SOD-123 Plastic Package.

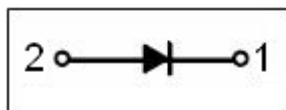
/ Features

Fast switching diodes. HF Product.

/ Applications

Small signal diode.

/ Equivalent Circuit



/ Pinning



PIN1:Cathode

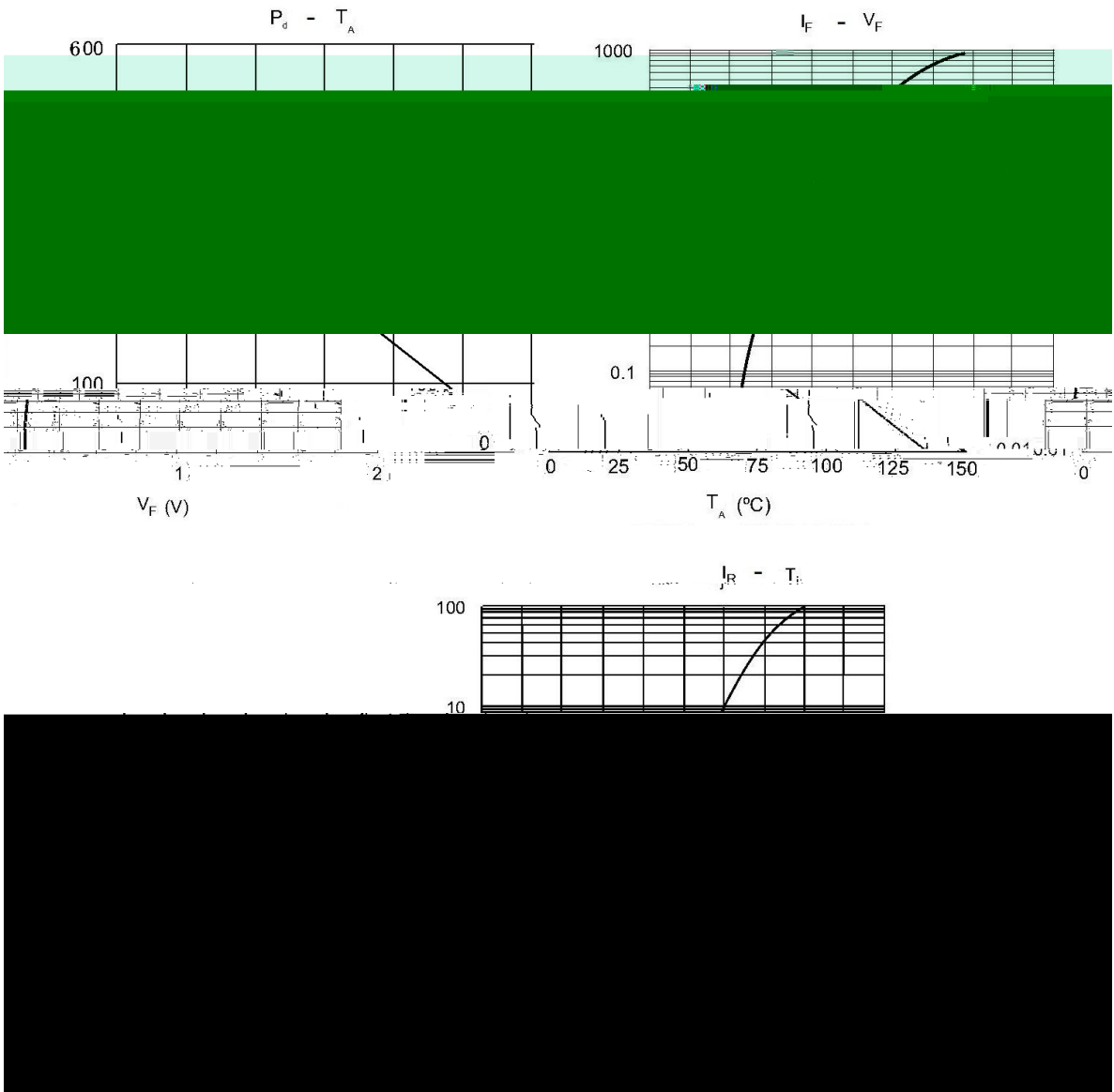
PIN2:Anode

/ h_{FE} Classifications & Marking

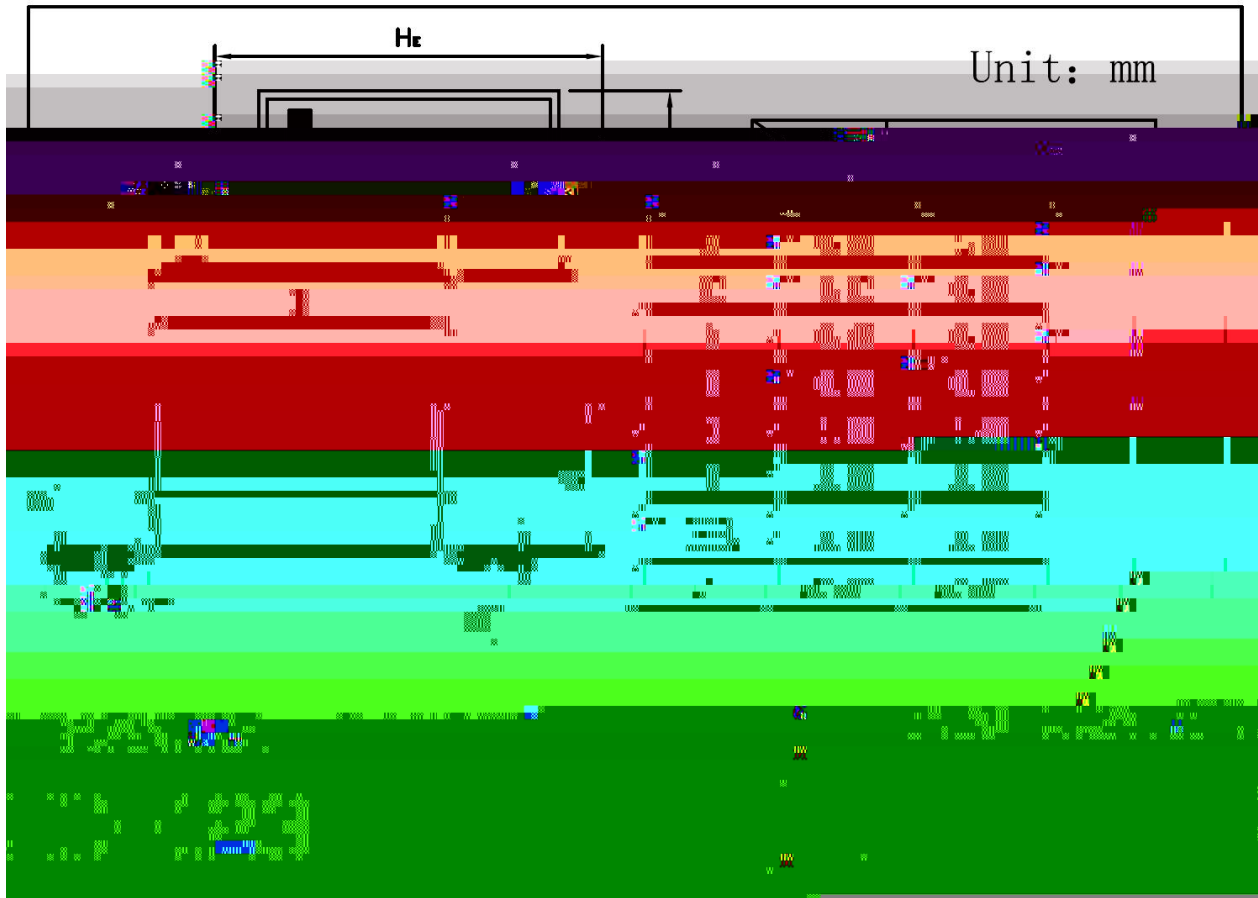
Model	BAV19W	BAV20W	BAV21W
Marking	HA8	HT2	HT3

Parameter	Symbol	Rating			Unit
		BAV19W	BAV20W	BAV21W	
Peak Repetitive Reverse Voltage	V_{RRM}	120	200	250	V
Working Peak Reverse Voltage DC Reverse Voltage	V_{RWM} V_R	100	150	200	V
RMS Reverse Voltage	$V_{R_{RMS}}$	71	106	141	V
Non-Repetitive Peak Forward Current	I_{FM}	400			mA
Output Current	I_O	200			mA
Non-Repetitive Peak Forward Surge Current	I_{FSM}	t=1.0μs:2.5A t=1.0s:0.5A			A
Power Dissipation	P_d	400			mW
Typical Thermal Resistance Junction to Ambient	$R_{\theta JA}$	500			/W
Junction and Storage Temperature Range	T_J, T_{stg}	-65 TO +150			

/ Electrical Characteristic Curve



/ Package Dimensions



/ Marking Instructions



H

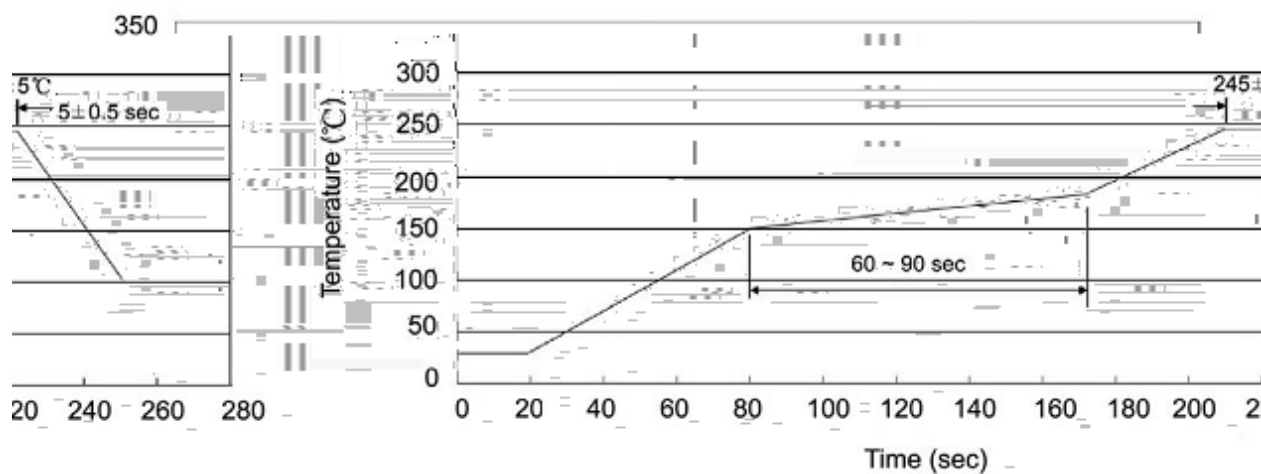
A8

Note:

H: Company Code.

A8: Product Type.

() / Temperature Profile for IR Reflow Soldering(Pb-Free)



Note:

- | | | | | | |
|---|-------|-----|-----------|--------|---|
| 1 | 150 | 180 | 60 | 90sec; | 1.Preheating:150~180 , Time:60~90sec. |
| 2 | 245±5 | | 5±0.5sec; | | 2.Peak Temp.:245±5 , Duration:5±0.5sec. |
| 3 | | 2 | 10 | /sec. | 3. Cooling Speed: 2~10 /sec. |

/ Resistance to Soldering Heat Test Conditions

260±5 10±1 sec. Temp.:260±5 Time:10±1 sec

/ Packaging SPEC.

/ REEL

Package Type	Units					Dimension		(unit mm ³)
	Units/Reel	Reels/Inner Box	Units/Inner Box	Inner Boxes/Outer Box	Units/Outer Box	Reel	Inner Box	